



Product Change Notification

Change Notification #: 116896 - 00
Change Title: Adding Desiccant Pouch Inside the Moisture Barrier Bag, PCN 116896-00, Transport Media, Adding Additional Desiccant Pouch & Relocating HIC Placement
Date of Publication: April 22, 2019

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

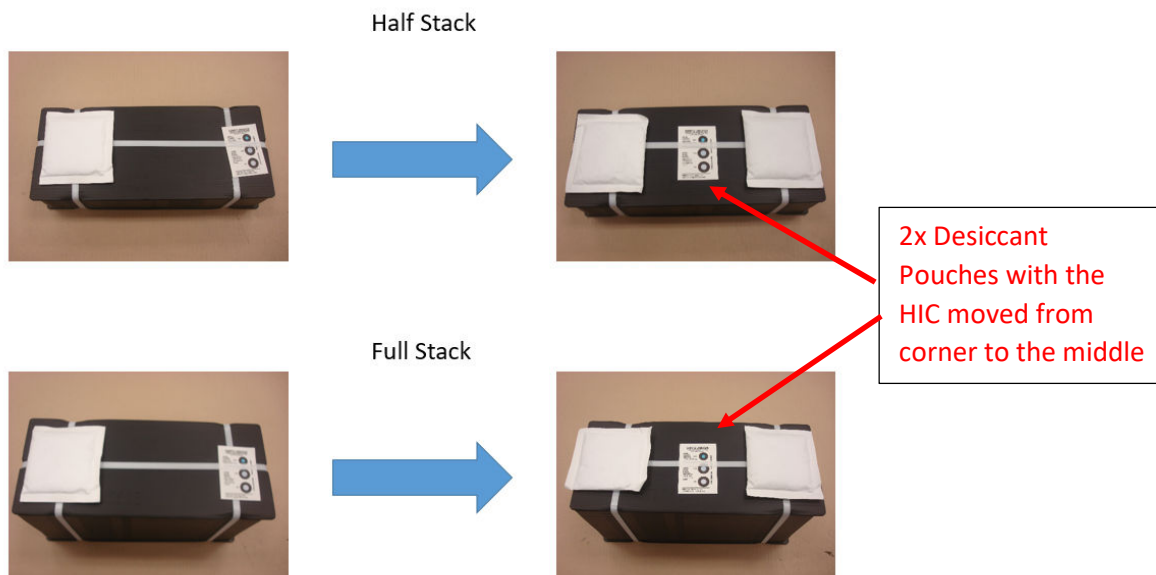
Date Customer Must be Ready to Receive Post-Conversion Material:	May 22, 2019
---	--------------

Description of Change to the Customer:

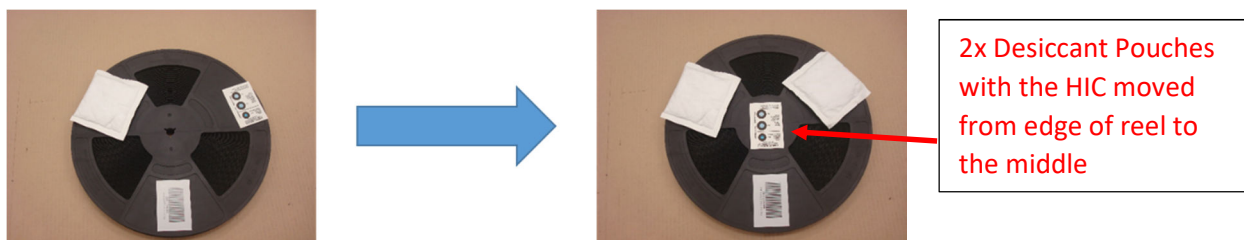
In order to address the marginality of coloration displayed on the Humidity Indicator Card (HIC) of desiccant packed products, Intel will be adding an additional desiccant pouch within the Moisture Barrier Bag. The additional desiccant pouch is exclusively for all Ball Grid Array (BGA) products that are Tray packed and shipped in either a Half-Height Intermediate Box (ie Half Stack) or a Full Intermediate Box (ie Full Stack) as well as all BGA products shipped in Tape & Reel.

As a result of adding the new desiccant pouch, the placement of the HIC will be moved to a new location in the middle of the tray stack or reel. (Pictures below are for example only)

TRAY PACKED



TAPE & REEL PACKED



Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product due to this change. Customers should, however, notify their inbound shipping/receiving personnel who may open up packaged materials and ensure they are aware of the change.

Intel will deplete older packaged material currently on shelves containing only the single desiccant pouch during the transition and therefore customers should expect to see a mix of packaging options until older packaged material has been depleted.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

The change will apply to all BGA Tray and Tape & Reel desiccant packed parts. In short, if products today are BGA products being shipped in Tray media in either a full intermediate box or a half-height box and include a desiccant pouch or Tape & Reel with a desiccant pouch, customers will now see the use of two desiccant pouches instead of one, with the HIC placed in the middle.

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
April 22, 2019	00	Originally Published PCN



Product Change Notification

116896 - 00

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apagcccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2018. Other names and brands may be claimed as the property of others.

3D XPoint, Axxia, Basis, Basis Peak, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, Curie, Flexpipe, Intel, the Intel logo, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Inside, the Intel Inside logo, Intel Insider, Intel Joule, Intel RealSense, Intel SingleDriver, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Intel XScale, InTru, the InTru logo, the InTru Inside logo, InTru soundmark, Iris, Itanium, MCS, MMX, Optane, Ostro, Pali, Pentium, picoArray, Picochip, picoXcell, Puma, Quark, SMARTi, Soletta, Sound Mark, StarPro, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcende, True Key, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS* Ready mark under license from Palm, Inc.

OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos.

Learn how to use Intel Trademarks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.